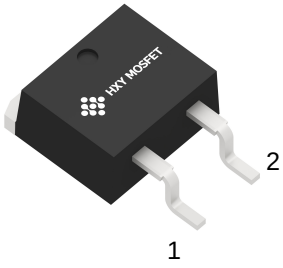
IDK08G120C5XTMA1

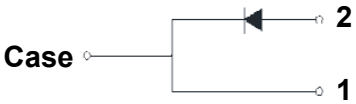
Silicon Carbide Schottky Diode

Features

- 1200-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F



TO-263N



Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives

Part Number	Package	Qty(PCS)
IDK08G120C5XTMA1	TO-263N	800

Maximum Ratings (T_C = 25 ˚C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V	
V_{RSM}	Surge Peak Reverse Voltage	1200	V	
I_F	Continuous Forward Current	23.9 11.3 8	A	T_C=25˚C T_C=135˚C T_C=152.5 ˚C
I_{FRM}	Repetitive Peak Forward Surge Current	48	A	T_C=25˚C, t_p = 10 ms, Half Sine Wave
I_{FSM}	Non-Repetitive Peak Forward Surge Current	96	A	T_C=25˚C, t_p = 10 ms, Half Sine Wave
P_{tot}	Power Dissipation	106 46	W	T_C=25˚C T_C=110˚C
T_J , T_{stg}	Operating Junction and Storage Temperature	-55 to +175	˚C	
$\int i^2dt$	i²dt value	46.08	A^2s	T_C=25˚C, t_p = 10 ms, Half Sine Wave

Electrical Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
V_{DC}	DC Blocking Voltage	1200			V	
V_F	Forward Voltage		1.45 1.99	1.7 2.5	V	I_F = 8 A T_J=25°C I_F = 8 A T_J=175°C
I_R	Reverse Current		3.5 17	50 100	μA	V_R = 1200 V T_J=25°C V_R = 1200 V T_J=175°C
Q_C	Total Capacitive Charge		38		nC	V_R = 800 V T_J = 25°C
C	Total Capacitance		595 38 30		pF	V_R = 0 V, T_J = 25°C, f = 1 MHz V_R = 400 V, T_J = 25°C, f = 1 MHz V_R = 800 V, T_J = 25°C, f = 1 MHz
E_C	Capacitance Stored Energy		20		μJ	V_R = 800 V

Thermal Characteristics

Symbol	Parameter	Typ.	Unit
$R_{\theta JC}$	Thermal Resistance from Junction to Case	1.41	°C/W

Typical Performance

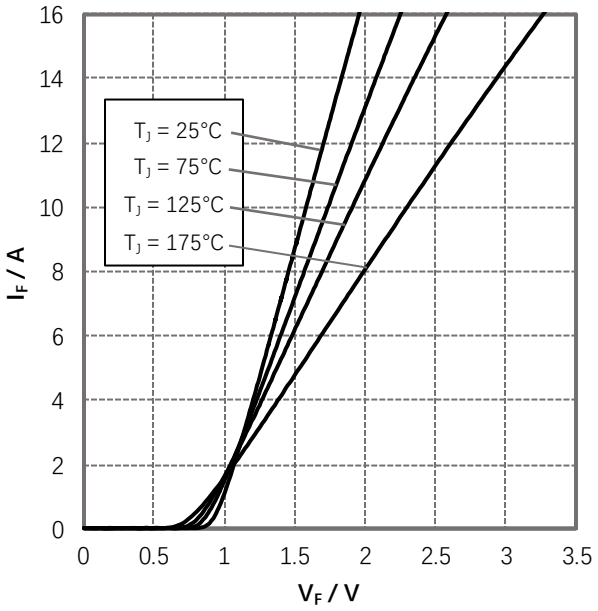


Figure 1. Forward Characteristics

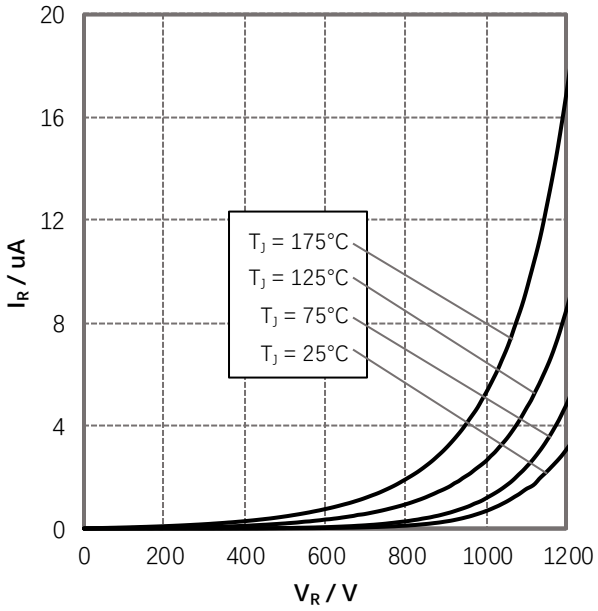


Figure 2. Reverse Characteristics

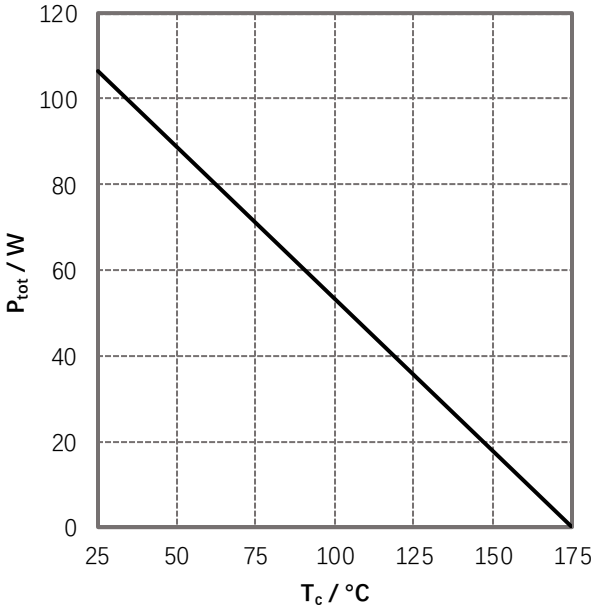


Figure 3. Power Derating

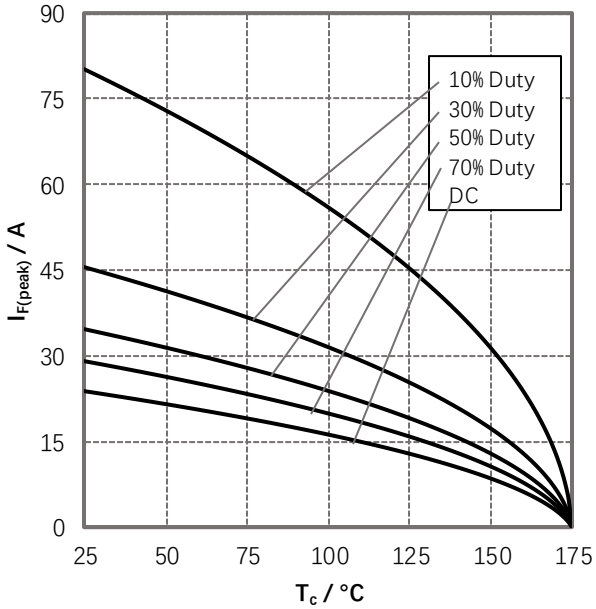


Figure 4. Current Derating

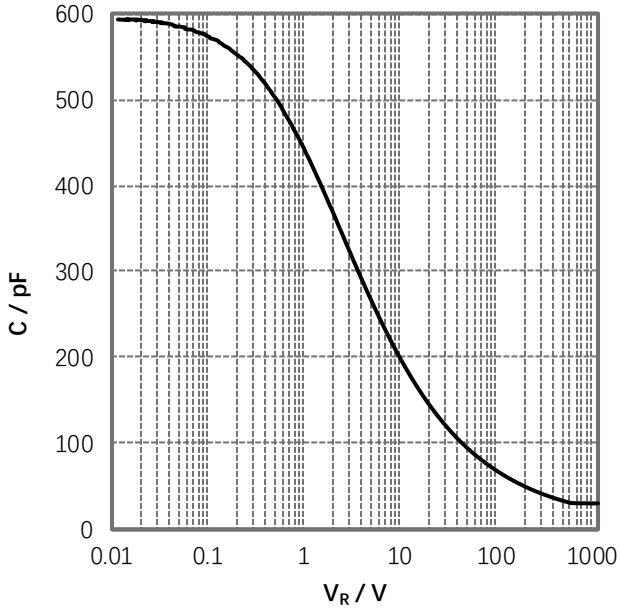


Figure 5. Capacitance vs. Reverse Voltage

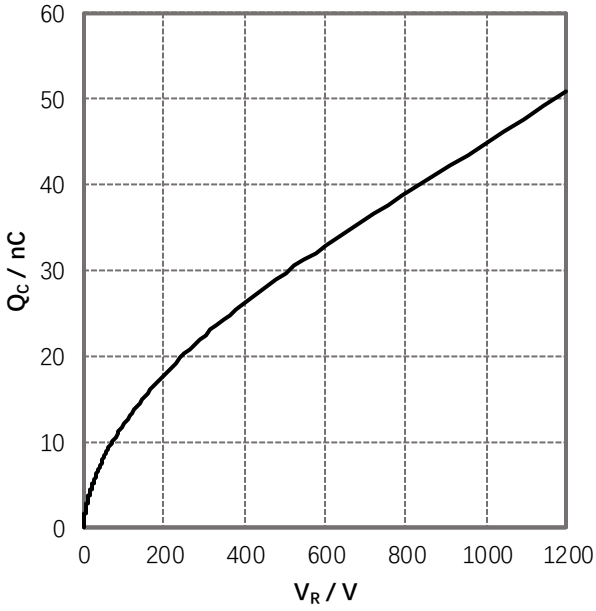


Figure 6. Total Capacitance Charge vs. Reverse Voltage

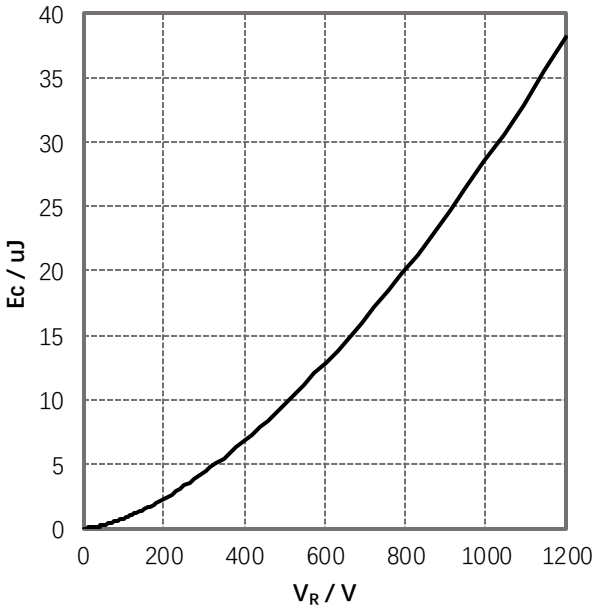


Figure 7. Capacitance Stored Energy

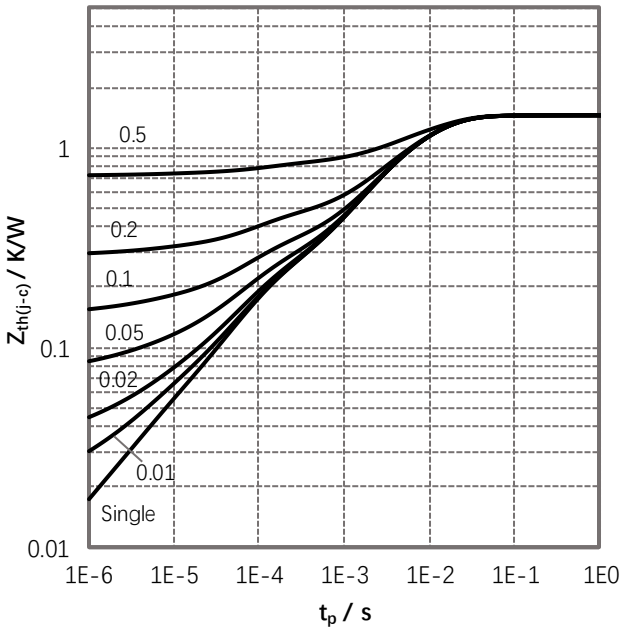
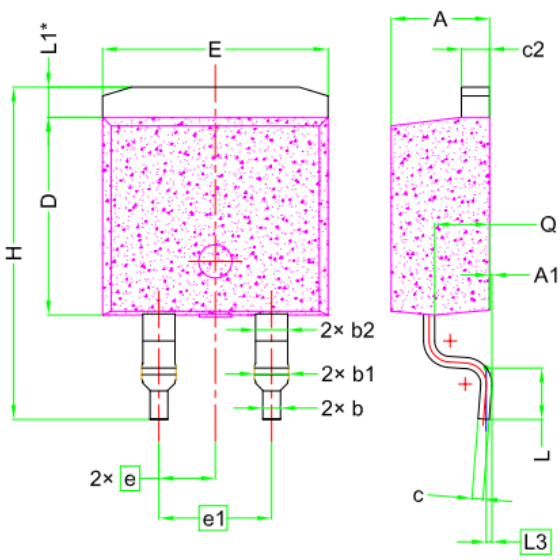
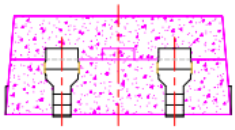


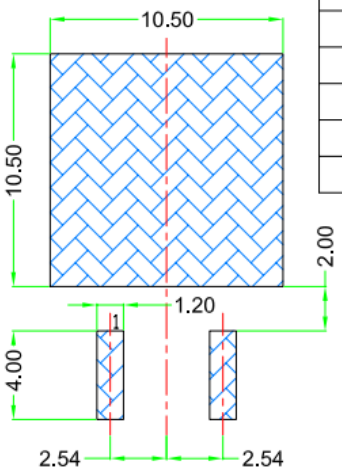
Figure 8. Transient Thermal Impedance

Package Information
TO-263N





Land Pattern
(Only for Reference)



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.24	4.44	4.64
A1	0.00	0.10	0.25
b	0.70	0.80	0.90
b1	1.20	1.55	1.75
b2	1.20	1.45	1.70
c	0.40	0.50	0.60
c2	1.15	1.27	1.40
D	8.82	8.92	9.02
D1	6.86	7.65	—
E	9.96	10.16	10.36
E1	6.89	7.77	7.89
e	2.54 BSC		
e1	5.08 BSC		
H	14.61	15.00	15.88
L	1.78	2.32	2.79
L1	1.36 REF.		
L3	0.25 BSC		
Q	2.30	2.48	2.70

Note:
1. All Dimensions Are In mm.
2. Dimension D & E Do Not Include Mold Flash.
   Mold Flash Shall Not Exceed 0.127mm Pre Side.
   These Dimensions Are Measured At The Outermost
   Extreme Of The Plastic Body.
3. Thermal Pad Contour Optional Within Dimensions E, L1, D1 & E1.
4. Dimension D1 & E1 Establish A Minmum Mounting Surface for
   The Thermal Pad.
5. "*" is reference .

Attention

■ Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.

■ HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.

■ Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

■ HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could
give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

■ In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

■ No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.

■ Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

■ Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.

Unikeyic Electronics

Global Electronic Components Distributor

Click to view pricing, inventory, delivery, and lifecycle information:

HXY MOSFET:

ESD5LM5.0C-HXY HRCLAMP3371ZCTFT PESDLC2FD3V3BH PESDNC2XD5VBF PJEC5V0M1FN2 HACPDQC5V0-HF HSEN2411D3 HSTS521050B331 PESDSC2FD5VU PJSD24CW_R1 RLSD32A121V 60N06 AQ15C-01FTG AZ4007-01H BV05C-H HAZ4007-01H HESD36VD3B LM393DR-HXY PESDNC2XD5VBL TPSMB100CA-VR HCEZ36V,L3F HESDSLC3V3D3B AZ4836-01L ESD5L5.0C-HXY HLY323BC1524L HSEN3611D3 HPTVSUC3D5VB HSD15C.TCT HSG3D15B3.3MA TPSMB28A-VR